

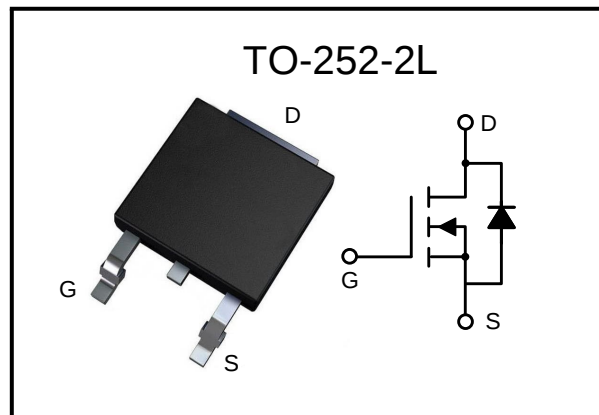
General Description

The BMI03N820 uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety applications.

Features

- $V_{DS}=30V$
- $I_D=45A$
- $R_{DS(ON)}@10V,TYP=8.2m\Omega$

Package



Application

- Power factor correction (PFC)
- Uninterruptible power supply (UPS)
- Switched mode power supplies (SMPS)
- LED lighting power

Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-Source Voltage		30	V
V_{GS}	Gate - Source Voltage		± 20	
I_D	Drain Current	$T_C=25^{\circ}C$	45	A
		$T_C=100^{\circ}C$	29	
I_{DM}	Drain Current-Pulse ⁽¹⁾		180	A
P_D	Power Dissipation	$T_C=25^{\circ}C$	45	W
		Derate above $25^{\circ}C$	0.35	W/ $^{\circ}C$
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾		90	mJ
T_J	Operation Junction Temperature Range		-55 to +150	$^{\circ}C$
T_{stg}	Storage Temperature Range		-55 to +150	$^{\circ}C$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient		62.5	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance From Junction to Case		2.0	$^{\circ}C/W$



Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D=250\mu A$	30	—	—	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30V, V_{GS}=0V$	—	—	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$	—	—	± 100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D=250\mu A$	1.0	1.5	1.8	V
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=15A$	—	8.2	11.0	m Ω
		$V_{GS}=4.5V, I_D=10A$	—	14.5	20.0	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 15V,$ $V_{GS} = 0V,$ $f = 1MHz$	—	860	—	pF
Output Capacitance	C_{oss}		—	145	—	
Reverse Transfer Capacitance	C_{rss}		—	110	—	
Gate Resistance	R_g	$V_{GS}=0V, f=1MHz$	1	3	10	Ω
Switching Characteristics ^(3,4)						
Turn-on Delay time	$T_{d(on)}$	$V_{DD}=20V,$ $V_{GS}=10V,$ $R_G = 6\Omega,$ $I_D = 15A$	—	6.2	—	ns
Turn-on Rise time	T_r		—	31.5	—	
Turn -Off Delay Time	$T_{d(off)}$		—	38.6	—	
Turn -Off Fall time	T_f		—	13.5	—	
Gate to Drain Charge	Q_g	$V_{DS}=15V,$ $V_{GS}=10V,$ $I_D=15A$	—	18.8	—	nC
Gate to Source Charge	Q_{gs}		—	6.9	—	
Gate to Drain Charge	Q_{gd}		—	4.3	—	
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=15A$	—	0.88	1.2	V
Continuous Source Current	I_S	Integral Reverse P-N Junction	—	—	45	A
Pulsed Source Current	I_{SM}	Diode in the MOSFET	—	—	180	
Reverse Recovery Time	T_{rr}	$I_F=15A, d_{IF}/d_t=100A/\mu s$	—	48	—	ns
Reverse Recovery Charge	Q_{rr}		—	52	—	nC

Notes:

- (1) Pluse width limited by maximum junction temperature.
- (2) $L=0.5mH, V_{DD}=15V, V_G=10V, R_G=25\Omega$, starting $T_J=25^{\circ}\text{C}$.
- (3) Pulse Test: Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$.
- (4) Essentially independent of operating temperature.



Typical Performance Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Figure 1: Output Characteristics

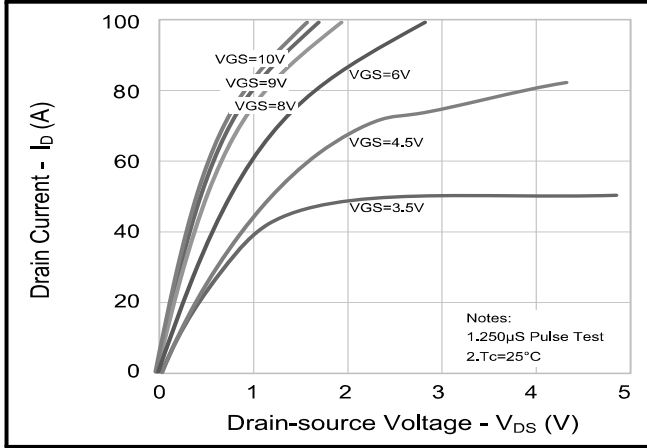


Figure 3: $R_{DS(ON)}$ vs. I_D

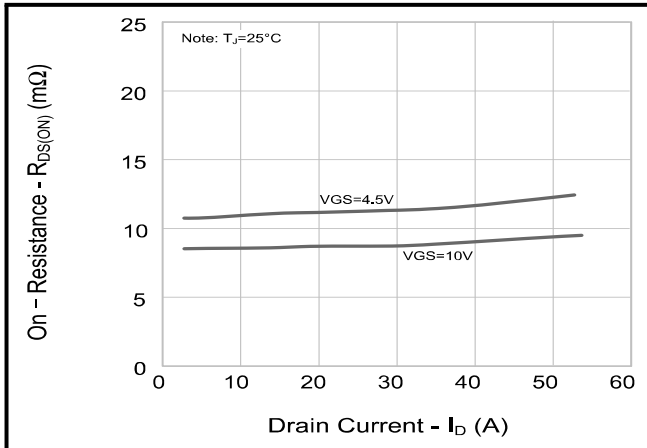


Figure 5: Capacitance Characteristics

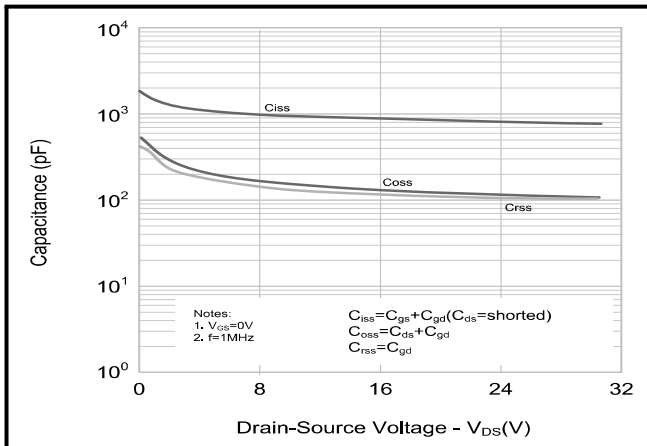


Figure 2: Transfer Characteristics

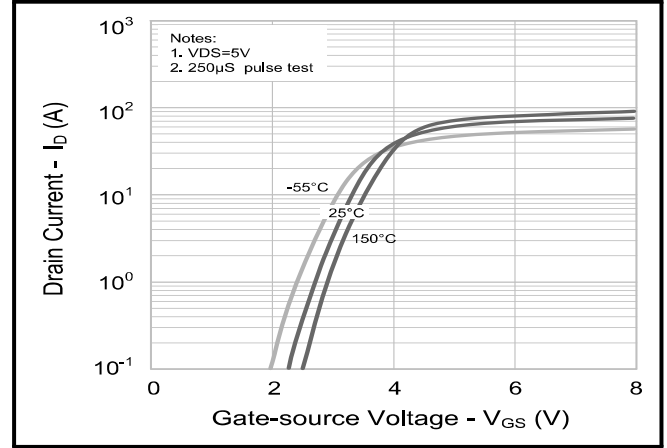


Figure 4: Body Diode Forward Voltage Variation vs. Source Current and Temperature

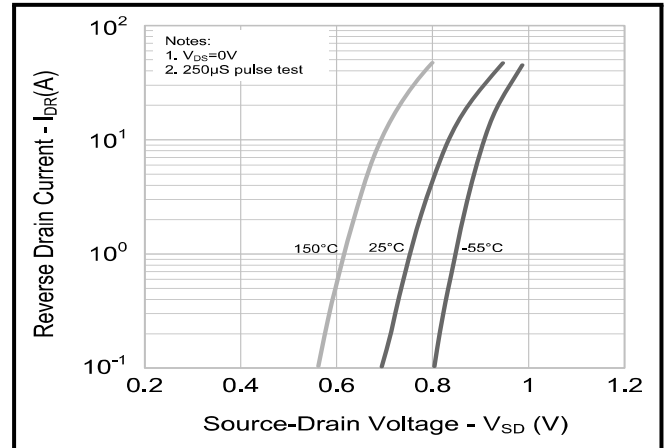
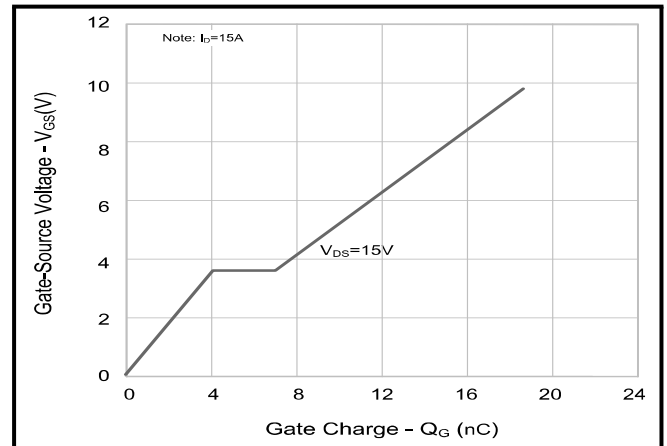


Figure 6: Gate Charge



Typical Performance Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Figure 7: Breakdown Voltage vs. Temperature Characteristics

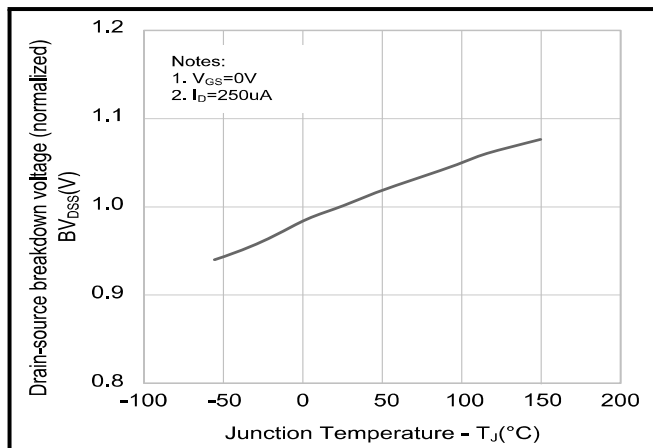


Figure 8: On-resistance vs. Temperature Characteristics

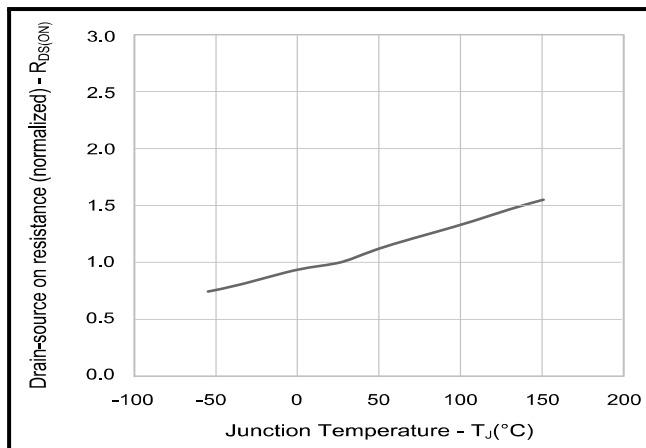
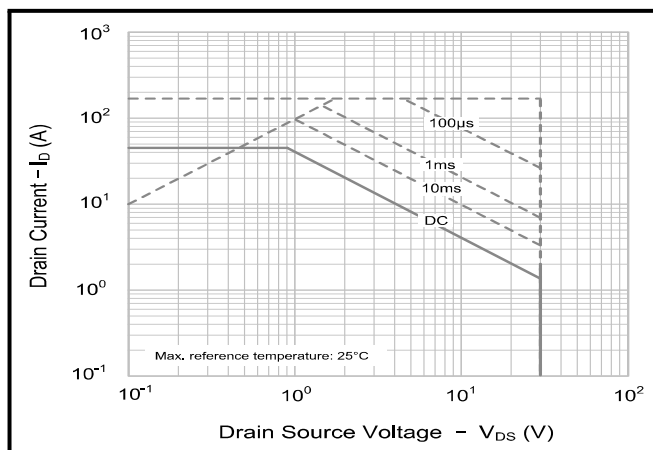


Figure 9: Max. Safe Operating Area



Test Circuit

Figure 10: Gate Charge Test Circuit

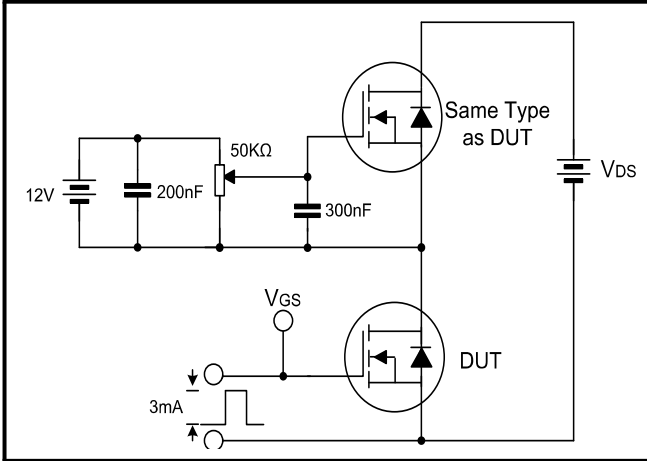


Figure 12: Resistive Switching Test Circuit

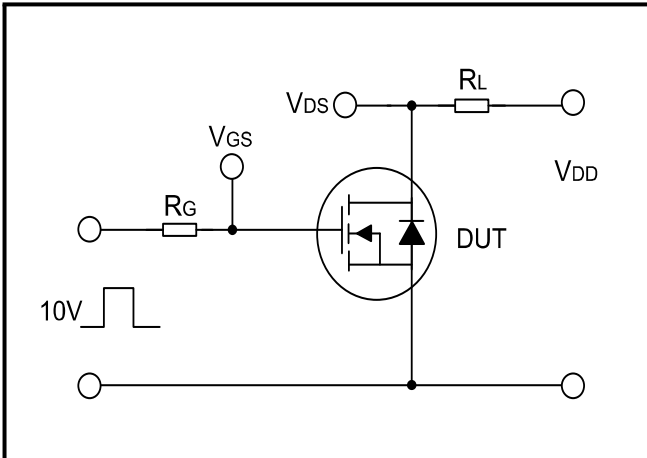


Figure 14: Unclamped Inductive Switching Test Circuit

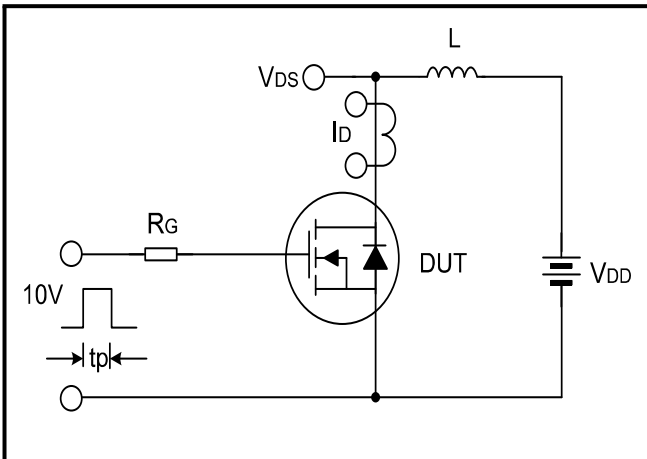


Figure 11: Gate Charge Waveform

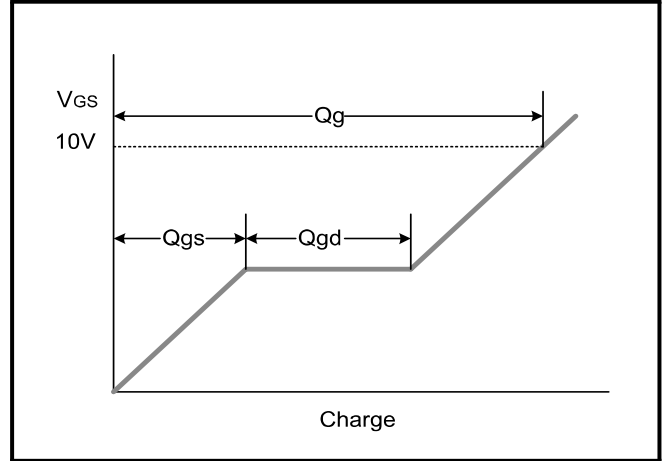


Figure 13: Resistive Switching Waveform

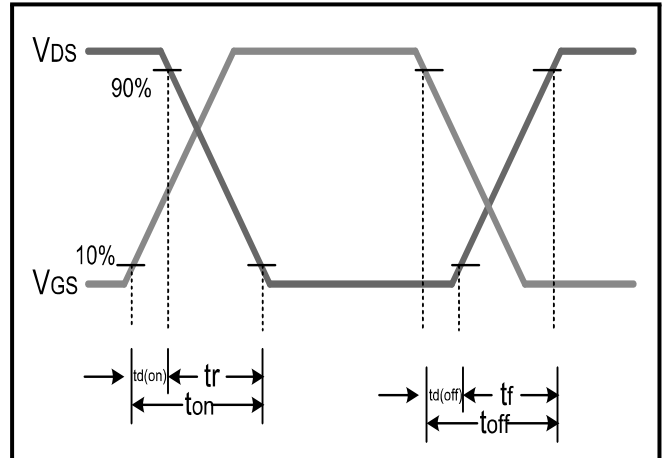
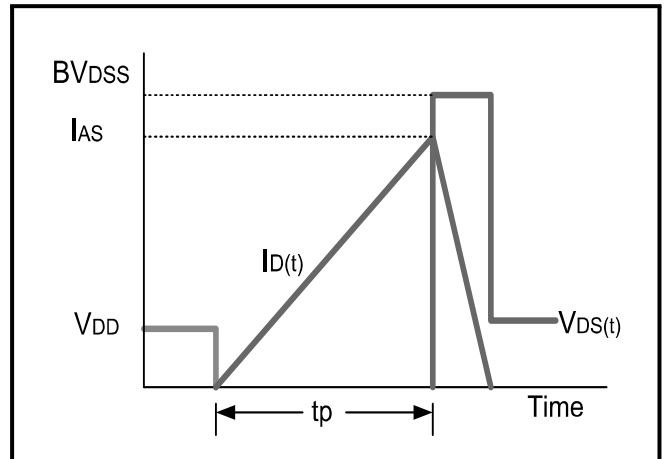
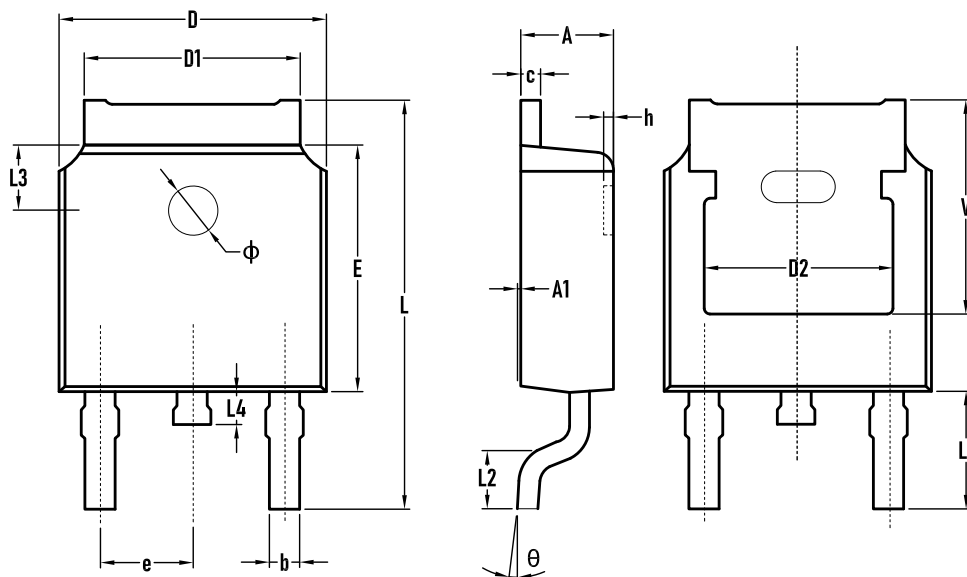


Figure 15: Unclamped Inductive Switching Waveform



Packaging Tape - TO-252-2



SYMBOL	Millimeters		Inches	
	MIN.	MAX.	MIN.	MAX.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

